

DRILL TABLE:

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
Q	399	7.87mil (0.200mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Q	1661	12.00mil (0.305mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Q	696	16.00mil (0.406mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Q	8	31.00mil (0.787mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	6	35.43mil (0.900mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	44	40.00mil (1.016mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	4	43.31mil (1.100mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	58	63.00mil (1.600mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	4	125.98mil (3.200mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
Y	12	254.00mil (6.452mm)	PTH	Round	TopLayer - BottomLayer	~+/- 3mil
	2888 Total					

STACKUP - DETAILS

Layer Name	Material	Thickness	Constant	Board Layer Stack
1 Top Overlay				
2 Top Solder	Solder Resist	0.80mil	3,5	
3 TopLayer	Copper	1.40mil		
4 Dielectric 1	FR-4 High Tg	4.90mil	4,4	
5 L2-GND	Copper	2.80mil		
6 Dielectric 2	FR-4 High Tg	5.12mil	4,4	
7 L3-Sig1	Copper	1.40mil		
8 Dielectric 3	FR-4 High Tg	5.13mil	4,4	
9 L4-GND	Copper	2.80mil		
10 Dielectric 4	FR-4 High Tg	5.12mil	4,4	
11 L5-Power	Copper	2.80mil		
12 Dielectric 5	FR-4 High Tg	5.29mil	4,4	
13 L6-GND	Copper	2.80mil		
14 Dielectric 6	FR-4 High Tg	5.12mil	4,4	
15 L7-Power	Copper	2.80mil		
16 Dielectric 7	FR-4 High Tg	5.21mil	4,4	
17 L8-Power	Copper	2.80mil		
18 Dielectric 8	FR-4 High Tg	5.12mil	4,4	
19 L9-GND	Copper	2.80mil		
20 Dielectric 9	FR-4 High Tg	5.25mil	4,4	
21 L10-Sig2	Copper	1.40mil		
22 Dielectric 10	FR-4 High Tg	5.12mil	4,4	
23 L11-GND	Copper	2.80mil		
24 Dielectric 11	FR-4 High Tg	4.90mil	4,4	
25 BottomLayer	Copper	1.40mil		
26 Bottom Solder	Solder Resist	0.80mil	3,5	
27 Bottom Overlay				

DESIGN INFORMATION	
MIN. TRACK WIDTH: 8 MIL	
MIN. CLEARANCE: 6 MIL	
MIN. VIA PAD SIZE: 19,7 MIL	
MINIMUM ANNUAL RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408 <input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER	
THICKNESS: <input type="checkbox"/> 62 MIL (1.6mm) +/-10% <input checked="" type="checkbox"/> OTHER 85 MIL +/-10%	
TOLERANCE: <input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2	
<input type="checkbox"/> OTHER +/-	
BOW & TWIST: <input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2	
<input type="checkbox"/> OTHER +/-	
DRILLING:	
REFERENCE: <input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES	
PTH COPPER THICKNESS: <input checked="" type="checkbox"/> 20-30 um <input type="checkbox"/> OTHER	
BOARD FINISH:	
SILKSCREEN: <input checked="" type="checkbox"/> TOP <input type="checkbox"/> BOTTOM	
SILKSCREEN COLOR: <input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER	
SOLDER RESIST COLOR: <input checked="" type="checkbox"/> GREEN <input type="checkbox"/> OTHER	
<input checked="" type="checkbox"/> MATTIE <input type="checkbox"/> SEMI-GLOSS	
SURFACE FINISH: <input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENERP	
<input type="checkbox"/> IMI, TM, SILVER OR EQUIV <input type="checkbox"/> OTHER	
ARRAY/PANEL: <input checked="" type="checkbox"/> CUT AND TRIM PER MI BOARD OUTLINE	
<input type="checkbox"/> N.C. ROUTE <input type="checkbox"/> V. SCORE	
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS -> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3	
<input checked="" type="checkbox"/> ROHS <input type="checkbox"/> OTHER PER ORDER	
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.	
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION: <input type="checkbox"/> YES	
BARE BOARD ELEC. TEST: <input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER	
<input type="checkbox"/> XX MIL VAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> XX MIL VAS REQUIRE CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> OUTER XX MIL VAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE	
<input type="checkbox"/> LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE	
<input type="checkbox"/> TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE	
TEXAS INSTRUMENTS	
PROJECT TITLE: BMCOSIA	
DESIGNED FOR: Public Release	
FILE NAME: BMCOSIA	
DESIGNER: Panidi, Ramasiddaiah	LAYOUT BY: PACTRON
SCALE: 1.00	ALTIM DESIGNER VERSION: 18.1.9.240

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